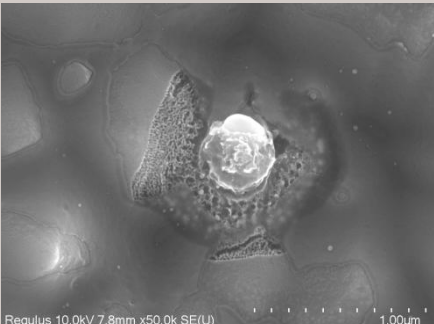
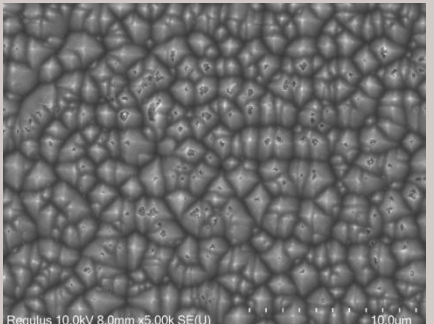


<p>适用场景 Application</p>	<p>适用于 N-TOPCon 叠加激光增强接触修复技术的正面细栅浆料，兼容正面非 SE 或 SE 工艺 N-TopCon Silver pastes for B-Doped Emitter, SE or homogeneous doping with laser induced firing process</p>
<p>印刷网版 Printing screen</p>	<p>适配 PI 无网结超细线网版、钢版等 PI knotless screen with ultra fine line finger pattern</p>
<p>亮点 Highlight</p>	<ul style="list-style-type: none"> 超细线网版下的高速印刷能力，可匹配 3-8um 线宽量产 Long time stability, high speed printing, 4-7.5 um fingers, mass production 兼容 SE 及非 SE，适配高方阻工艺 Customized for SE and non-SE process for high sheet resistance emitter 较宽的工艺窗口，在超低单耗，依然具有优异的 EL 表现 Robust contact designed for Various firing process Good EL for low laydown or low firing temperature 自主材料，在效率及可靠性的平衡方面，有更多的调整方案，快速且稳定 Self designed raw materials & formula, well. Balanced between eff & reliability 适用于各种烧结炉、光注入炉、激光等设备 Suitable for various sintering furnace, light injected & laser induced firing furnace <div style="display: flex; justify-content: space-around;"> <div data-bbox="379 1122 815 1532">  <p>“银硅”合金 Ag-Si alloy</p> </div> <div data-bbox="849 1122 1284 1532">  <p>良好的浆料接触 Good paste contact</p> </div> </div>

N 型电池正面细栅的超细线形貌：

Ultra-fine finger morphology on N-type cell front

